

# ELECTRONICS APPLICATIONS



EPOXY ELECTRICAL ENCAPSULATING COMPOUND		SYSTEM NUMBER	MIX RATIO PARTS BY WT. A: PARTS BY WT. B:	MIXED VISCOSITY CPS @ 25°C	POTLIFE @25°C 100g. MASS	CURE SCHEDULE	SPECIFIC GRAVITY	HARDNESS SHORE "D"	GLASS TRANSITION TEMP°C	DELECTRIC STRENGTH V/mil	VOLUME RESISTIVITY (OHM-CM)
<b>SS1803</b> <b>SA1803</b> <b>SB1803</b>	EPMAR SS1803 IS A BLACK, LOW VISCOSITY, TWO COMPONENT ELECTRONIC GRADE POTTING COMPOUND. EXCELLENT PHYSICAL AND ELECTRICAL CHARACTERISTICS AS WELL AS EASY HANDLING MAKE THIS RESIN/HARDENER COMBINATION IDEAL FOR THE ENCAPSULATION OF ELECTRONIC MODULES. SS1803 HAS A HIGH GLOSS SURFACE APPEARANCE.	<b>SS1803</b> <b>SA1803</b> <b>SB1803</b>	100/42	995	40 MINUTES	24HRS @ RT or 3HRS @ 60°C	1.12	85	65	540	3.1x10 <sup>15</sup>
<b>SS1804</b> <b>SA1804</b> <b>SB1803</b>	EPMAR SA1804/SB1803 IS A BLACK FILLED, TWO COMPONENT, ROOM TEMPERATURE CURING EPOXY POTTING COMPOUND. SS1804 WAS SPECIFICALLY DEVELOPED FOR ELECTRONIC MODULE POTTING APPLICATIONS. EXCELLENT ELECTRICAL AND PHYSICAL PROPERTIES COMBINED WITH EASY HANDLING, SELF DEAIRATION AND A HIGH GLOSS SURFACE APPEARANCE.	<b>SS1804</b> <b>SA1804</b> <b>SB1803</b>	100/30	890	60 MINUTES	24HRS @ RT or 3HRS @ 60°C	1.19	80	66	510	4.6x10 <sup>14</sup>
<b>SS1836X</b> <b>SA1836X</b> <b>SB1836X</b>	EPMAR SS1836X IS A BLACK, TWO COMPONENT, FLAME RETARDANT, FILLED EPOXY. SS1836X WAS DEVELOPED FOR THE POTTING OF ELECTRONIC MODULES. U.L. LISTED 94V0. SS1836X HAS EXCELLENT THERMAL PROPERTIES, LOW SHRINKAGE AND LOWER COEFFICIENT OF THERMAL EXPANSION.	<b>SS1836X</b> <b>SA1836X</b> <b>SB1836X</b>	100/100 OR 1/1 BY VOLUME	10,600	120 MINUTES	24HRS @ RT or 3HRS @ 60°C	1.52	76	40	410	3.0x10 <sup>14</sup>
<b>SS1873</b> <b>SA1873</b> <b>SB1873</b>	EPMAR SS1873 IS A TWO COMPONENT, FILLED EPOXY COMPOUND. THE COMPOUND CONSISTS OF SA1873 FILLED RESIN AND SB1873 FILLED HARDENER. SS1873 COMPOUND WAS DEVELOPED SPECIFICALLY FOR THE POTTING OF ELECTRIC AND ELECTRONIC MODULES. SS1873 EXHIBITS OUTSTANDING TENSILE STRENGTH AND CRACK RESISTANCE UNDER EXTREME CONDITIONS.	<b>SS1873</b> <b>SA1873</b> <b>SB1873</b>	100/100 OR 1/1 BY VOLUME	4720	90 MINUTES	24-36HRS @ RT or 3HRS @ 60°C	1.61	85	40	500	1.5x10 <sup>14</sup>
<b>SS1874</b> <b>SA1874</b> <b>SB1874</b>	EPMAR SS1874 IS A CLEAR, TWO COMPONENT, ROOM TEMPERATURE CURING EPOXY COMPOUND. SS1874 WAS DEVELOPED FOR APPLICATIONS WHERE A CLEAR CASTING COMPOUND IS REQUIRED. EXCELLENT ELECTRICAL AND PHYSICAL PROPERTIES.	<b>SS1874</b> <b>SA1874</b> <b>SB1874</b>	100/42	760	60 MINUTES	7DAYS @ RT or 4HRS @ 80°C	1.10	80	68	515	3.1x10 <sup>14</sup>
<b>SS1875</b> <b>SA1875</b> <b>SB1875</b>	EPMAR SS1875 IS A TWO COMPONENT, FILLED EPOXY COMPOUND. THE COMPOUND CONSISTS OF PART A FILLED RESIN AND PART B FILLED HARDENER. SS1875 WAS DEVELOPED SPECIFICALLY FOR THE POTTING OF ELECTRICAL AND ELECTRONIC MODULES. SS1875 HAS EXCELLENT THERMAL PROPERTIES, LOW SHRINKAGE AND LOWER COEFFICIENT OF THERMAL EXPANSION.	<b>SS1875</b> <b>SA1875</b> <b>SB1875</b>	100/100 OR 1/1 BY VOLUME	6590	90 MINUTES	24-36HRS @ RT or 3HRS @ 60°C	1.61	87	42	500	1.5x10 <sup>14</sup>
<b>SS1919</b> <b>SA1919</b> <b>SB1919</b>	EPMAR SS1919 IS A LOW VISCOSITY, CLEAR AMBER, 100% SOLIDS EPOXY SYSTEM. SS1919 MEETS THE REQUIREMENTS OF F.D.A. 175.105. SS1919 HAS EXCELLENT ADHESION TO MOST SUBSTRATES AND HAS HIGH CHEMICAL RESISTANCE. FORMUATED FOR THE FILTER MARKET.	<b>SS1919</b> <b>SA1919</b> <b>SB1919</b>	100/40	750	10 MINUTES	24HRS @ RT or 4HRS @ 80°C	1.09	90	57	520	8.0x10 <sup>14</sup>
<b>SS1920</b> <b>SA1920</b> <b>SB1920</b>	EPMAR SS1920 IS A WHITE, TWO COMPONENT, HEAT CURE EPOXY DEVELOPED FOR ELECTRONIC APPLICATIONS. SS1920 WAS DEVELOPED FOR THE POTTING AND ENCAPSULATION OF ELECTRONIC COMPONENTS AND CIRCUITRY. IT IS A FLAME RETARDED COMPOUND CONTAINING NO HALOGENS OR ANTIMONY OXIDE. FORMULATED FOR THE FLY BACK TRANSFORMER MARKET - UL94V0.	<b>SS1920</b> <b>SA1920</b> <b>SB1920</b>	100/35	1090	8 HOURS	90MIN @ 70°C plus 3HRS @ 115°C	1.61	90	114	560	5.9x10 <sup>14</sup>
<b>POLYURETHANES</b>											
<b>SS2017</b> <b>SA2017</b> <b>SB2017</b>	EPMAR SS2017 IS A TWO COMPONENT, UNFILLED, 100% SOLIDS MDI BASED POLYURETHANE POTTING AND CASTING COMPOUND SPECIFICALLY DEVELOPED FOR TELECOMMUNICATION CONNECTOR BLOCKS.	<b>SS2017</b> <b>SA2017</b> <b>SB2017</b>	100/150	825	12 MINUTES	GEL: 18MIN@RT 7-10 DAYS@RT	1.10	60	-80	480	3.1x10 <sup>13</sup>
<b>SS2057</b> <b>SA2057</b> <b>SB2057</b>	EPMAR SS2057 IS A TWO-COMPONENT, SEMI-TRANSPARENT, POLYURETHANE ENCAPSULATING COMPOUND. COMPONENT "A" IS A POLYMERIC ISOCYANATE AND COMPONENT "B" IS BASED ON HYDROPHOBIC POLYOLS. THE CURED ELASTOMER IS SOFT (55 WITH "00" SCALE DUROMETER), VERY FLEXIBLE AND HAS EXCELLENT ELECTRICAL AND THERMAL SHOCK RESISTANCE. THIS ELECTRICAL INSULATING RESIN COMPOUND IS DESIGNED ESPECIALLY FOR REENTERABLE SPLICE PROTECTION.	<b>SS2057</b> <b>SA2057</b> <b>SB2057</b>	16.5/83.5	700	40 MINUTES	GEL: 60MIN 5 DAYS @ RT or 8HRS @ 100F°	1	55-60 00 TYPE	N/A	N/A	3.0x10 <sup>12</sup>